

*This listing of claims will replace all prior versions, and listings, of claims in the application:*

**Listing of Claims:**

**Claims 1-12 (Canceled).**

**Claim 13 (Currently Amended):** A linear chemical mechanical planarization (CMP) system, comprising:

    a pair of rollers;

    a belt pad disposed on the rollers, the belt pad having a first portion comprised of a first pad material and a second portion comprised of a second pad material, and the belt pad having a reference notch;

    a wafer carrier disposed above a surface of the belt pad; and

    a control system for controlling a rotation of the rollers, the control system being configured to determine a location of the second portion of the belt pad relative to the wafer carrier by using the reference notch, and the control system being configured to stop rotation of the rollers such that the second portion of the belt pad is aligned under the wafer carrier.

**Claim 14 (Original):** The CMP system of claim 13, wherein the first portion of the belt pad is configured for barrier removal.

**Claim 15 (Original):** The CMP system of claim 13, wherein the first pad material is comprised of polyurethane.

**Claim 16 (Original):** The CMP system of claim 13, wherein the second portion of the belt pad is configured for buffing.

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**Claim 17 (Original):** The CMP system of claim 13, wherein the second pad material is comprised of porous rubber.

**Claims 18 and 19 (Canceled).**